



JAPANESE
INDUSTRIAL
STANDARD

Translated and Published by
Japanese Standards Association

JIS C 6524 : 1995

**Prepreg for multilayer printed wiring
boards—Bismaleimide/Triazine/
Epoxide resin impregnated glass
cloth**

ICS 31.180

Descriptors : printed-circuit bases, glass, thermoplastic polymers, substrates
(insulating)

Reference number : JIS C 6524 : 1995 (E)

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In the event of any doubts arising as to the contents,
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Printed in Japan

Prepreg for multilayer printed wiring boards
—Bismaleimide/Triazine/Epoxide resin impregnated glass cloth

1 Scope This Japanese Industrial Standard specifies prepreg of bismaleimide/triazine/epoxide resin impregnated glass cloth for multilayer printed wiring boards (hereafter referred to as “prepreg”).

Remarks : The following standards are cited in this Standard:

JIS C 5603 *Terms and definitions for printed circuits*

JIS C 6494 *Thin copper-clad laminates for multilayer printed wiring boards – Glass fabric base, Bismaleimide/Triazine/Epoxide*

JIS C 6520 *General rules of prepreg for multilayer printed wiring boards*

JIS C 6521 *Test methods of prepreg for multilayer printed wiring boards*

2 Definitions For the purpose of this Standard, in addition to the definitions specified in JIS C 5603 and JIS C 6520, the following definition apply:

modified polyphenylene oxide resin Such a resin that polyphenylene oxide resin is added to and mixed with bismaleimide/triazine/epoxide resin, then cured.

Informative reference : In general, polyphenylene oxide resin is called PPO, but it is not accepted in the United States of America since the symbol PPO is a registered trademark. Accordingly, the symbol PPE lead from the chemical name “polyphenylene ether” is used in U.S.A. and in a part of Japan.

3 Type designation

3.1 Structure of type designation The type designation shall be structured by arranging the symbols as follows:

[Symbol denoting prepreg]	[Hyphen]	[Symbol denoting base material and binder]	[Symbol denoting character- istics]	[Symbol denoting thickness after molding]	[Symbol denoting resin flow]
[3.2.1]		[3.2.2]	[3.2.3]	[3.2.4]	[3.2.5]
Example: P	–	GT	1F	08	10

3.2 Symbols

3.2.1 Prepreg The symbol denoting prepreg shall be an English capital letter P, based on the provision of 3.2.1 in JIS C 6520.

3.2.2 Base material and binder The symbol denoting base material and binder shall be the English capital letters GT which denote the bismaleimide/triazine/epoxide resin impregnated glass cloth, based on the provision of 3.2.2 in JIS C 6520.